

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IGB50N65S5	**Issued**	17. May 2021
MA#	MA005414052		
Package	PG-TO263-3-2	**Weight***	1560.11 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.704	0.17	0.17	1733	1733
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.49	19.52	194875	195129
wire	non noble metal	aluminium	7429-90-5	6.960	0.45	0.45	4461	4461
encapsulation	inorganic material	zincoxide	1314-13-2	6.846	0.44		4388	
	miscellaneous	miscellaneous	-	27.385	1.76		17553	
	plastics	epoxy resin	-	102.694	6.58		65825	
	inorganic material	silicondioxide	60676-86-0	547.700	35.11	43.89	351065	438831
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6190	6190
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.063			40	
	noble metal	silver	7440-22-4	0.078			50	
	non noble metal	lead	7439-92-1	2.992	0.19	0.19	1918	2008
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.10	35.15	351044	351501
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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